East 8 WPIDJPO

] [Number	Hits	Socret Tout		
+	1	1625192		DB	Time stamp
		1020132	Compor paterna or remova	JPO;	2004/10/15 10:36
12	2	2012874	(bond\$ pad) or (contact pad)	DERWENT	
		== 120,7	(contact pau)	JPO;	2004/10/15 10:37
3	3	307877	resist or photoresist or mask or photomask	DERWENT	
]	resist of photoresist of mask of photomask	JPO;	2004/10/15 10:38
4	ļ	17602	passivat\$	DERWENT	
		,,,,,,	ρασσιναιφ	JPO;	2004/10/15 10:38
5	,	641458	adhes\$	DERWENT	
				JPO;	2004/10/15 10:38
6	i	2225243	adhes\$ layer	DERWENT	
			and layo,	JPO;	2004/10/15 10:38
7	•	17348	(etch\$ or patern\$ or remov\$) and ((bond\$ pad) or (contact	DERWENT	
			pad)) and (resist or photoresist or mask or photomask) and	JPO;	2004/10/15 10:39
			(passivat\$ or (adhes\$ layer))	DERWENT	
8		36628	(bond\$ with pad) or (contact with pad)	ID C	
			(contact with pau)	JPO;	2004/10/15 10:39
9		149036	adhes\$ with layer	DERWENT	
			,	JPO;	2004/10/15 10:40
1	0.	8016	(etch\$ or patern\$ or remov\$) with (adhes\$ with layer)	DERWENT	
		\ /	(adhest with layer)	JPO;	2004/10/15 10:40
1	1	7928	passivat\$ with layer	DERWENT	
				JPO;	2004/10/15 10:40
1:	2	1765	(etch\$ or patern\$ or remov\$) with (passivat\$ with layer)	DERWENT	
1			(passivate with layer)	JPO;	2004/10/15 10:40
13	3	635	(((etch\$ or patern\$ or remov\$) with (adhes\$ with layer)) or	DERWENT	
			((etch\$ or patern\$ or remov\$) with (passivat\$ with layer)))	JPO;	2004/10/15 10:41
			and (resist or photoresist or mask or photomask) and	DERWENT	
	ľ	1	((bond\$ pad) or (contact pad))		
14	1	635	(etch\$ or patern\$ or remov\$) and (((etch\$ or patern\$ or	JPO;	2004/40/45 40 44
	İ		remov\$) with (adhes\$ with laver)) or ((etch\$ or natern\$ or	DERWENT	2004/10/15 10:41
ĺ	. 1	,	remov\$) with (passivat\$ with layer))) and (resist or	DEITWENT	1
l		ļ	photoresist or mask or photomask) and ((bond\$ pad) or		
١			(contact pad)))	Í	1
15		20586	bond\$ with pad	JPO;	2004/10/15 10:41
				DERWENT	2004/10/15 10:41
16		73	((etch\$ or patern\$ or remov\$) and ((((etch\$ or patern\$ or	JPO;	2004/10/15 11:15
		1	remova) with (adhesa with laver)) or ((etcha or naterna or	DERWENT	2004/10/15 11.15
ĺ			remova) with (passivata with laver))) and (resist or	OLIK VEIV	
			photoresist or mask or photomask) and ((bond\$ pad) or		
47	İ		(contact pad)))) and (bond\$ with nad)		
17		562	((etch\$ or patern\$ or remov\$) and (((etch\$ or patern\$ or	JPO;	2004/10/15 11:15
			remova) with (adhesa with laver)) or ((etchs or naterns or	DERWENT	200 11 101 10 11.15
	ŀ	1	remov\$) with (passivat\$ with laver))) and (resist or		
			photoresist or mask or photomask) and ((bond\$ nad) or		
18		J.	(contact pad)))) not (bond\$ with pad)		
10		57	(((etch\$ or patern\$ or remov\$) and ((((etch\$ or patern\$ or	JPO;	2004/10/15 11:15
			remova) with (adhesa with laver)) or ((etcha or paterna or	DERWENT	
	ŀ	1.0	remova) with (passivat\$ with laver))) and (resist or		
	-		photoresist or mask or photomask) and ((bond\$ pad) or		
			(contact pad)))) not (bond\$ with pad)) and solder\$		

est & WPID, JPO L Number DB Time stamp 1625192 etch\$ or patern\$ or remov\$ JPO; 2004/10/15 10:36 DERWENT 2 2012874 (bond\$ pad) or (contact pad) JPO: 2004/10/15 10:37 DERWENT 3 307877 resist or photoresist or mask or photomask JPO: 2004/10/15 10:38 **DERWENT** 4 17602 passivat\$ JPO: 2004/10/15 10:38 DERWENT 5 641458 adhes\$ JPO: 2004/10/15 10:38 DERWENT 6 2225243 adhes\$ layer JPO: 2004/10/15 10:38 DERWENT 7 17348 (etch\$ or patern\$ or remov\$) and ((bond\$ pad) or (contact JPO: 2004/10/15 10:39 pad)) and (resist or photoresist or mask or photomask) and **DERWENT** (passivat\$ or (adhes\$ layer)) 8 36628 (bond\$ with pad) or (contact with pad) JPO: 2004/10/15 10:39 DERWENT 9 149036 adhes\$ with layer JPO: 2004/10/15 10:40 DERWENT 10 8016 (etch\$ or patern\$ or remov\$) with (adhes\$ with layer) JPO: 2004/10/15 10:40 DERWENT 11 7928 passivat\$ with layer JPO: 2004/10/15 10:40 DERWENT 12 1765 (etch\$ or patern\$ or remov\$) with (passivat\$ with layer) JPO: 2004/10/15 10:40 DERWENT 13 635 (((etch\$ or patern\$ or remov\$) with (adhes\$ with layer)) or JPO: 2004/10/15 10:41 ((etch\$ or patern\$ or remov\$) with (passivat\$ with layer))) DERWENT and (resist or photoresist or mask or photomask) and ((bond\$ pad) or (contact pad)) 14 635 (etch\$ or patern\$ or remov\$) and ((((etch\$ or patern\$ or JPO: 2004/10/15 10:41 remov\$) with (adhes\$ with layer)) or ((etch\$ or patern\$ or DERWENT remov\$) with (passivat\$ with layer))) and (resist or photoresist or mask or photomask) and ((bond\$ pad) or (contact pad))) 15 20586 bond\$ with pad JPO; 2004/10/15 10:41 DERWENT 16 ((etch\$ or patern\$ or remov\$) and ((((etch\$ or patern\$ or JPO; 2004/10/15 11:15 remov\$) with (adhes\$ with layer)) or ((etch\$ or patern\$ or DERWENT remov\$) with (passivat\$ with layer))) and (resist or photoresist or mask or photomask) and ((bond\$ pad) or (contact pad)))) and (bond\$ with pad) 17 562 ((etch\$ or patern\$ or remov\$) and (((etch\$ or patern\$ or JPO: 2004/10/15 11:15 remov\$) with (adhes\$ with layer)) or ((etch\$ or patern\$ or DERWENT remov\$) with (passivat\$ with layer))) and (resist or photoresist or mask or photomask) and ((bond\$ pad) or (contact pad)))) not (bond\$ with pad) 18 (((etch\$ or patern\$ or remov\$) and ((((etch\$ or patern\$ or JPO; 2004/10/15 11:25 remov\$) with (adhes\$ with layer)) or ((etch\$ or patern\$ or **DERWENT** remov\$) with (passivat\$ with layer))) and (resist or photoresist or mask or photomask) and ((bond\$ pad) or (contact pad)))) not (bond\$ with pad)) and solder\$ 19 505 (((etch\$ or patern\$ or remov\$) and ((((etch\$ or patern\$ or JPO: 2004/10/15 11:26 remov\$) with (adhes\$ with layer)) or ((etch\$ or patern\$ or DERWENT remov\$) with (passivat\$ with layer))) and (resist or photoresist or mask or photomask) and ((bond\$ pad) or (contact pad)))) not (bond\$ with pad)) not ((((etch\$ or patern\$ or remov\$) and ((((etch\$ or patern\$ or remov\$) with (adhes\$ with layer)) or ((etch\$ or patern\$ or remov\$) with (passivat\$ with layer))) and (resist or photoresist or mask or photomask) and ((bond\$ pad) or (contact pad)))) not (bond\$ with pad)) and solder\$)

V	20	33	((((etch\$ or patern\$ or remov\$) and ((((etch\$ or patern\$ or remov\$) with (adhes\$ with layer)) or ((etch\$ or patern\$ or remov\$) with (passivat\$ with layer))) and (resist or photoresist or mask or photomask) and ((bond\$ pad) or (contact pad)))) not (bond\$ with pad)) not (((etch\$ or patern\$ or remov\$) and ((((etch\$ or patern\$ or remov\$) with (adhes\$ with layer)) or ((etch\$ or patern\$ or remov\$) with (passivat\$	JPO; DERWENT	2004/10/15 11:33
	21	472	with layer))) and (resist or photoresist or mask or photomask) and ((bond\$ pad) or (contact pad)))) not (bond\$ with pad)) and solder\$)) and ("438" or "216") (((etch\$ or patern\$ or remov\$) and (((etch\$ or patern\$ or remov\$) with (adhes\$ with layer)) or ((etch\$ or patern\$ or remov\$) with (passivat\$ with layer))) and (resist or photoresist or mask or photomask) and ((bond\$ pad) or	JPO; DERWENT	2004/10/15 11:33
	22	8	(contact pad)))) not (bond\$ with pad)) not ((((etch\$ or patern\$ or remov\$) and ((((etch\$ or patern\$ or remov\$) with (adhes\$ with layer)) or ((etch\$ or patern\$ or remov\$) with (passivat\$ with layer))) and (resist or photoresist or mask or photomask) and ((bond\$ pad) or (contact pad)))) not (bond\$ with pad)) and solder\$)) not ((((etch\$ or patern\$ or remov\$) and ((((etch\$ or patern\$ or remov\$) with (adhes\$ with layer))) or ((etch\$ or patern\$ or remov\$) with (passivat\$ with layer))) and (resist or photoresist or mask or photomask) and ((bond\$ pad) or (contact pad)))) not (bond\$ with pad)) not ((((etch\$ or patern\$ or remov\$) with (adhes\$ with layer))) or ((etch\$ or patern\$ or remov\$) with (passivat\$ with layer)) or ((etch\$ or patern\$ or remov\$) with (passivat\$ with layer))) and (resist or photoresist or mask or photomask) and ((bond\$ pad) or (contact pad)))) not (bond\$ with pad)) and solder\$)) and ("438" or "216")) ((((etch\$ or patern\$ or remov\$) and ((((etch\$ or patern\$ or	JPO;	2004/10/15 11:35
	,		remov\$) with (adhes\$ with layer)) or ((etch\$ or patern\$ or remov\$) with (passivat\$ with layer))) and (resist or photoresist or mask or photomask) and ((bond\$ pad) or (contact pad)))) not (bond\$ with pad)) not (((etch\$ or patern\$ or remov\$) with (adhes\$ with layer)) or ((etch\$ or patern\$ or remov\$) with (passivat\$ with layer))) and (resist or photoresist or mask or photomask) and ((bond\$ pad) or (contact pad)))) not (bond\$ with pad)) and solder\$)) not ((((etch\$ or patern\$ or remov\$) with (adhes\$ with layer))) or ((etch\$ or patern\$ or remov\$) with (passivat\$ with layer))) and (resist or photoresist or mask or photomask) and ((bond\$ pad) or (contact pad)))) not (bond\$ with pad)) not (((etch\$ or patern\$ or remov\$) and (((etch\$ or patern\$ or remov\$) with (passivat\$ or patern\$ or remov\$) with (adhes\$ with layer))) and (resist or photoresist or mask or photomask) and ((bond\$ pad) or (contact pad)))) not (bond\$ pad) or (contact pad)))) not (bond\$ pad) or (contact pad)))) not (bond\$ with pad)) and solder\$)) and ("438" or "216"))) and ("156" or "437" or "257")	DERWENT	

23 464	(((((etch\$ or patern\$ or remov\$) and ((((etch\$ or patern\$ or remov\$) with (adhes\$ with layer)) or ((etch\$ or patern\$ or remov\$) with (passivat\$ with layer))) and (resist or photoresist or mask or photomask) and ((bond\$ pad) or (contact pad)))) not (bond\$ with pad)) not ((((etch\$ or patern\$ or remov\$) with (adhes\$ with layer))) or ((etch\$ or patern\$ or remov\$) with (passivat\$ with layer))) and (resist or photoresist or mask or photomask) and ((bond\$ pad) or (contact pad)))) not (bond\$ with pad)) and solder\$)) not ((((etch\$ or patern\$ or remov\$) with (passivat\$ with layer))) or ((etch\$ or patern\$ or remov\$) with (passivat\$ with layer))) and (resist or photoresist or mask or photomask) and ((bond\$ pad) or (contact pad)))) not (bond\$ with pad)) not ((((etch\$ or patern\$ or remov\$) and ((((etch\$ or patern\$ or remov\$) and (((etch\$ or patern\$ or remov\$)) with (passivat\$ with layer))) or ((etch\$ or patern\$ or remov\$) with (passivat\$ with layer))) and (resist or photoresist or mask or photomask) and ((bond\$ pad) or (contact pad)))) not (bond\$ with pad)) and solder\$)) and ("438" or "216"))) not (((((etch\$ or patern\$ or remov\$) with (passivat\$ with layer))) or ((etch\$ or patern\$ or remov\$) with (passivat\$ with layer))) and (resist or photoresist or mask or photomask) and (((etch\$ or patern\$ or remov\$) with (passivat\$ with layer))) and (resist or photoresist or mask or photomask) and (((etch\$ or patern\$ or remov\$) with (passivat\$ with layer))) or ((etch\$ or patern\$ or remov\$) with (passivat\$ with layer))) or ((etch\$ or patern\$ or remov\$) with (passivat\$ with layer))) or ((etch\$ or patern\$ or remov\$) with (passivat\$ with layer))) or ((etch\$ or patern\$ or remov\$) with (passivat\$ with layer))) or ((etch\$ or patern\$ or remov\$) with (passivat\$ with layer))) or ((etch\$ or patern\$ or remov\$) with (passivat\$ with layer))) and (resist or patern\$ or remov\$) with (passivat\$ with layer))) and (resist or patern\$ or remov\$) with (passivat\$ with layer))) and (resist or patern\$ or remov\$) with (passivat\$ with layer))) and (resist or patern	JPO; DERWENT	2004/10/15 11:35
	remov\$) with (passivat\$ with layer))) and (resist or photoresist or mask or photomask) and ((bond\$ pad) or (contact pad)))) not (bond\$ with pad)) and solder\$)) not ((((etch\$ or patern\$ or remov\$) and (((etch\$ or patern\$ or		